



NOTES

- MATERIAL:  
HSG: NYLON, GLASS-FILLED, UL94V-0 COLOR: BLACK  
PIN: 0.50mm SQ, COPPER ALLOY
- PLATING TYPE:
  - GOLD FLASH OVER  
1.270µm MIN. NICKEL OVERALL.
  - GOLD FLASH ON CONTACT AND  
1.905µm MIN. TIN ON SOLDER TAIL OVER  
1.270µm MIN. NICKEL OVERALL.
  - 0.254µm MIN. GOLD PLATE ON CONTACT AND  
1.905µm MIN. TIN ON SOLDER TAIL OVER  
1.270µm MIN. NICKEL OVERALL.
  - 0.381µm MIN. GOLD PLATE ON CONTACT AND  
1.905µm MIN. TIN ON SOLDER TAIL OVER  
1.270µm MIN. NICKEL OVERALL.
  - 0.762µm MIN. GOLD PLATE ON CONTACT AND  
1.905µm MIN. TIN ON SOLDER TAIL OVER  
1.270µm MIN. NICKEL OVERALL.
  - 2.540µm MIN. TIN OVERALL  
1.270µm MIN. NICKEL OVERALL
- PRODUCT SPECIFICATION: PS-87761-100
- PACKAGING TYPE: SEE TABLE
- WAFER TO BE FLAT WITHIN 0.003 mm/mm
- COPLANARITY IS TO BE MEASURED BY RESTING THE SOLDER TAIL ON A GAUGE SURFACE
- IRREGULAR CIRCUIT CUTOFF WITHIN BREAKAWAY SECTION IS PERMISSIBLE. CUTTING OR CHIPPING OF THE MAIN BODY IS NOT ACCEPTABLE
- RECOMMENDED PCB THICKNESS IS 1.60mm±0.10
- THE ABOVE CKT 10 IS FOR ILLUSTRATION PURPOSE ONLY
- PACKAGING SPECIFICATION:  
TRAY: PK-89990-487  
T&R : PK-89990-484 / PK-87858-300  
TUBE: RPK-87979-1007 FOR ASSEMBLY 87979-1007.

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION											
DIMENSION UNITS		SCALE		CURRENT REV DESC: BRIGHT TIN PHASE OUT							
MM		NTS									
GENERAL TOLERANCES (UNLESS SPECIFIED)											
		MM		INCH							
4 PLACES		±		±							
3 PLACES		±		±							
2 PLACES		±		0.2		±					
1 PLACE		±		±		±					
0 PLACES		±		±		±					
ANGULAR TOL		±		3.0°							
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS				THIRD ANGLE PROJECTION		DRAWING		SERIES		MATERIAL NUMBER	
						A3-SIZE		87979		SEE TABLE	
								CUSTOMER		GENERAL MARKET	
										SHEET NUMBER	
										1 OF 2	

